1. (Currently Amended) An electronic component comprising:

a leadframe~~,~~;

a platform;

~~on which~~ an electronic member ~~is~~ located on the platform and connected to the leadframe by electrical conductors~~,~~; and

a housing which encloses the electronic member and the platform, where~~in~~ first and second support regions are provided on the platform on corresponding peripheral portions to support the platform during fabrication of the housing, ~~and~~ where~~in~~ at least a portion of the first and second support regions project beyond the housing subsequent to the fabrication of the housing~~are co-axial and the first support region is accessible via a first hole in a first wall surface of the housing and the second support region is accessible via a second hole in a second wall surface of the housing, wherein the first and second wall surfaces are substantially perpendicular~~.

2. (Currently Amended) The electronic component of claim 1, where~~in~~ the first and second support regions each comprise~~s~~ a lobe element~~ molded onto the platform~~.

3. (Cancelled)

4. (Cancelled)

5. (Currently Amended) The electronic component of claim 14, further comprising a transition zone located between the lobe element and a remaining portion of the platform, where

~~wherein~~ at least one notch-shaped depression is provided within ~~along a~~ the transition zone ~~between the lobe element and the platform~~.

6. (Cancelled)

7. (Currently Amended) The electronic component of claim 1~~6~~, where~~in~~ the leadframe further comprises at least one connecting piece that protrudes from the housing, where the at least one connecting piece is connected to the electronic member ~~is molded onto the platform forming a single piece~~.

8. (Currently Amended) The electronic component of claim 1~~5~~, where~~in~~ the leadframe further comprises a plurality of ~~at least three~~ connecting pieces that each protrude from the housing, where each connecting piece is connected to the electronic member~~are provided which run in parallel and are guided on one side of the housing out of the housing and are each electrically connected to the electronic member~~.

9. (Currently Amended) The electronic component of claim 1~~8~~, where~~in~~ the leadframe comprises a metal alloy.

10. (Currently Amended) The electronic component of claim 1~~2~~, where~~in~~ a thin anticorrosive film extends along at least a section of the lobe element.

11. (Currently Amended) The electronic component of claim 1~~0~~, where~~in~~ at least a section of a~~the~~ surface of the leadframe is coated with an metal alloy~~ which comprises Zn-Pb~~.

12. (Cancelled)

13. (Currently Amended) The electronic component of claim 1, wherein the electronic member comprises a Hall effect sensing device.

14. (New) A method of forming a housing around at least a portion of an electronic component, comprising the steps of:

providing the electronic component with a leadframe, a platform and an electronic member located on the platform, the electronic member being connected with the platform;

providing the platform with at least first and second support regions that each extend a predetermined distance beyond a periphery of the platform;

placing the electronic component within a molding die having an upper and a lower molding shell such that the first and second support regions of the platform contact at least one of the upper and lower molding shells;

injecting molding material into the molding die to form the housing around at least a portion of the electronic component; and

removing the electronic component from the molding die.

15. (New) The method of claim 14, where at least one of the upper and lower molding shells includes a recess to accommodate the first and second support regions of the platform during the step of placing.

16. (New) The method of claim 14, where a portion of each of the first and second support regions protrudes from beyond the housing after the step of removing.